

Series 352000 and 353000 PLCC-to-DIP Adapter

FEATURES

- Converts PLCC packaged IC-to-DIP footprints
- Ideal for prototyping and testing/evaluation
- · Available with PLCC sockets or PLCC pads on top side
- · Consult factory for Panelized Form or for mounting of consigned ICs

GENERAL SPECIFICATIONS

- ADAPTER BODY: 0.062 [1.58] thick, FR-4 with 1-oz. Cu traces
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE-AMS-QQ-N-290
- OPTIONAL PLCC SOCKETS: UL 94V-0 PPS
- SOCKET CONTACTS: Phosphor Bronze
- SOCKET CONTACT PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 50µ [1.27µ] Ni per SAE AMS-QQ-290
- CURRENT RATING: 1 amp
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
- Will plug into standard IC socket
- See Table for Pad Layout when mounting PLCC socket

ALL DIMENSIONS: INCHES [MILLIMETERS] ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.





Pins	Dim. "A"	Dim. "B"	Dim. "C"	Dim. "D"	Dim. "W" ±0.003 [0.08] non-cumulative	Dim. "X" ±0.003 [0.08] non-cumulative	Dim "Y" ±0.003 [0.08]	Dim. "Z" ±0.003 [0.08]	Pad Size
20	1.000 [25.4]	0.900 [22.86]	0.500 [12.7]	0.500 [12.7]	0.200 [5.08]	0.200 [5.08]	0.350 [8.89]	0.350 [8.89]	0.024 x 0.076 [0.61 x 1.93]
28	1.400 [35.56]	1.300 [33.02]	0.705 [17.91]	0.705 [17.91]	0.300 [7.62]	0.300 [7.62]	0.549 [13.95]	0.449 [11.41]	0.024 x 0.076 [0.61 x 1.93]



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